



Form Type	Distribute	Version	Ref	IPC 1752A	Sections	Material Info	Subsectional	D
<b>Supplier Information</b>								
<b>Company Name</b>	TE Connectivity	<b>Request Doc ID</b>		<b>Contact Name</b>	TE Product Compliance	<b>Contact Title</b>		
<b>Company Unique ID</b>	TE Connectivity	<b>Response Date</b>	2021-07-02	<b>Contact Email</b>	productcompliance@te.com			
<b>Contact Phone Number</b>	+001-800-522-6752							
<b>Legal Statement</b>								
<b>Supplier Acceptance</b>	true							
<b>Legal Statement</b>								
Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.								
<b>Product</b>								
<b>Manufacturer Item Number</b>	2041110-1	<b>Amount</b>	1.1707446	<b>Version</b>	-	<b>Identity</b>		
<b>Manufacturer Item Name</b>	PCI-E 4H Type I/G/F	<b>Weight UOM</b>	g	<b>Mfr Site</b>		<b>Authority</b>		
<b>Date</b>	2021-07-02							
<b>Product Disclosure</b>								
<b>Sub-Item/Material Level</b>	<b>Name</b>	<b>Substance Category</b>	<b>Substance CAS</b>	<b>Substance Concentration</b>	<b>Quantity</b>	<b>Mass per Unit</b>	<b>UOM</b>	<b>Exemption</b>
Sub Item 1	mSATA/mini PCI-E 4H Type I/G/F				1	1.1707446	g	
Material 2	Lower Contact-Ni plating					0.001976	g	
Substance 3	LEAD		7439-92-1	0.1000000000		0.000001976	g	
Substance 3	CONTAINS NO REPORTABLE TES081-2 SUBSTANCES		TE5081-2-0909	0.4000000000		0.000007904	g	
Substance 3	NICKEL		7440-02-0	99.5000000000		0.00196512	g	
Material 2	Upper Contact-Ni plating					0.003614	g	
Substance 3	NICKEL		7440-02-0	99.5000000000		0.00359593	g	
Substance 3	LEAD		7439-92-1	0.1000000000		0.000003614	g	
Substance 3	CONTAINS NO REPORTABLE TES081-2 SUBSTANCES		TE5081-2-0909	0.4000000000		0.000014456	g	
Material 2	Lower Contact					0.0858	g	
Substance 3	IRON		7439-89-6	0.0081000000		0.000006498	g	
Substance 3	COPPER		7440-50-8	94.1562000000		0.0807860196	g	
Substance 3	TIN		7440-31-5	5.6665000000		0.004861897	g	
Substance 3	PHOSPHORUS		7723-14-0	0.0807000000		0.0000692406	g	
Substance 3	LEAD		7439-92-1	0.0030000000		0.000002574	g	
Substance 3	CONTAINS NO REPORTABLE TES081-2 SUBSTANCES		TE5081-2-0909	0.0850000000		0.00007293	g	
Substance 3	ZINC		7440-66-6	0.0005000000		4.29E-7	g	
Material 2	Solder PEGS-Ni plating					0.00027	g	
Substance 3	CONTAINS NO REPORTABLE TES081-2 SUBSTANCES		TE5081-2-0909	0.4000000000		0.00000108	g	
Substance 3	LEAD		7439-92-1	0.1000000000		2.7E-7	g	
Substance 3	NICKEL		7440-02-0	99.5000000000		0.00026865	g	
Material 2	Upper Contact					0.4716	g	
Substance 3	IRON		7439-89-6	0.0081000000		0.0000138996	g	
Substance 3	ZINC		7440-66-6	0.0005000000		8.58E-7	g	
Substance 3	TIN		7440-31-5	5.6665000000		0.009723714	g	
Substance 3	LEAD		7439-92-1	0.0030000000		0.000005148	g	
Substance 3	COPPER		7440-50-8	94.1562000000		0.1615720392	g	
Substance 3	CONTAINS NO REPORTABLE TES081-2 SUBSTANCES		TE5081-2-0909	0.0850000000		0.00014586	g	
Substance 3	PHOSPHORUS		7723-14-0	0.0807000000		0.0001384812	g	
Material 2	Upper Contact-Au plating					0.0000338	g	
Substance 3	CONTAINS NO REPORTABLE TES081-2 SUBSTANCES		TE5081-2-0909	0.3000000000		1.014E-7	g	
Substance 3	GOLD		7440-57-5	99.7000000000		0.0000336986	g	
Material 2	Lower Contact-Au plating					0.0000208	g	
Substance 3	CONTAINS NO REPORTABLE TES081-2 SUBSTANCES		TE5081-2-0909	0.3000000000		6.24E-8	g	
Substance 3	GOLD		7440-57-5	99.7000000000		0.0000207376	g	
Material 2	Solder PEGS					0.0226	g	
Substance 3	IRON		7439-89-6	0.0082000000		0.0000018532	g	
Substance 3	COPPER		7440-50-8	64.2300000000		0.01451598	g	
Substance 3	LEAD		7439-92-1	0.0057000000		0.0000012883	g	
Substance 3	ZINC		7440-66-6	35.7546000000		0.0008005396	g	
Substance 3	PHOSPHORUS		7723-14-0	0.0015000000		3.39E-7	g	
Material 2	Housing					0.8843	g	
Substance 3	1,3-BENZENE DICA RBOXYLIC ACID, POLYMER WITH 1,4-BENZENE DICA RBOXYLIC ACID, (1,1'-BI(PHENYLENE)-4,4'-DIOL AND 4-HYDROXYBENZOIC ACID		60088-52-0	100.0000000000		0.8843	g	
Material 2	Solder PEGS-Sn plating					0.00093	g	
Substance 3	TIN		7440-31-5	99.9001000000		0.0005294705	g	
Substance 3	LEAD		7439-92-1	0.0999000000		5.2947E-7	g	